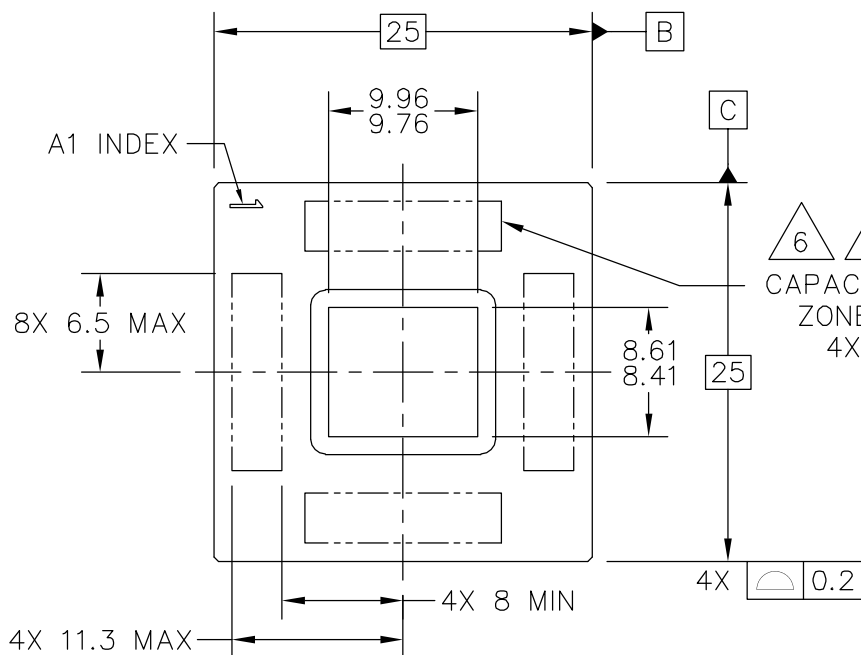
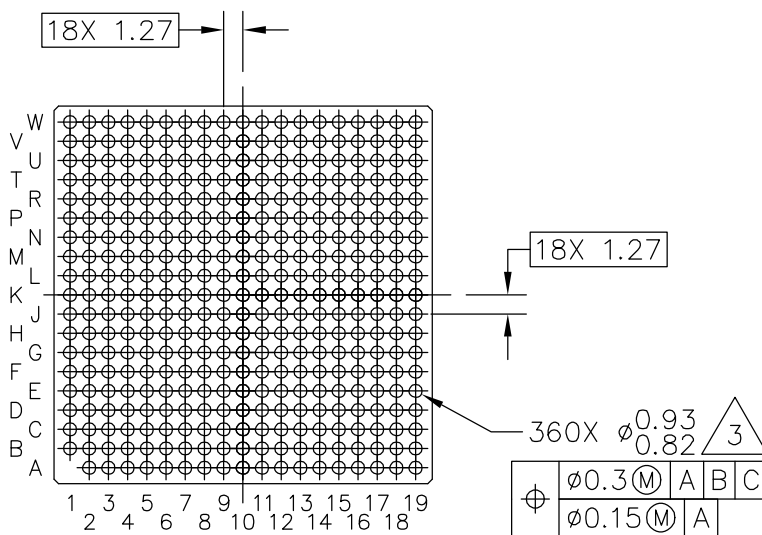
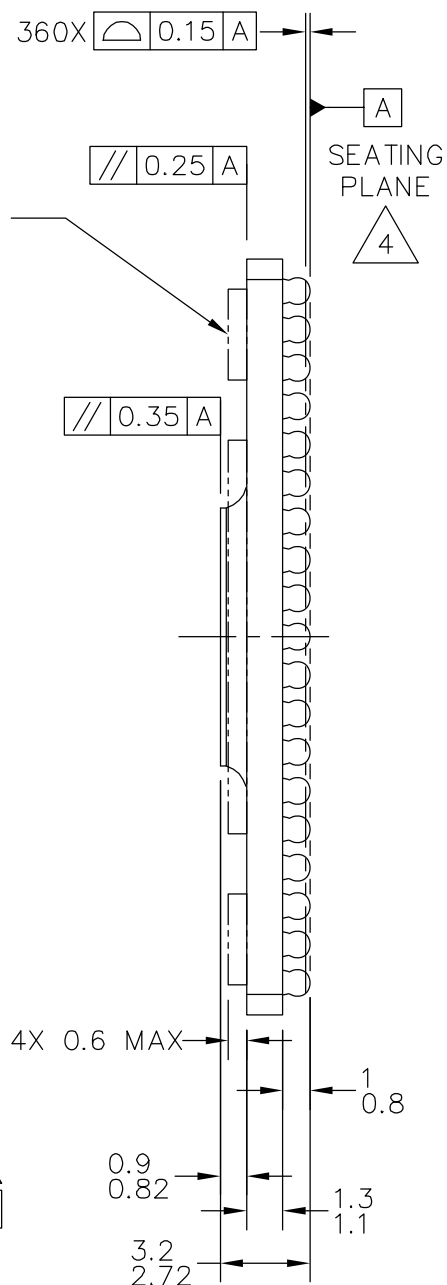




TOP VIEW



BOTTOM VIEW



SIDE VIEW

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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: 360 I/O FC CBGA,
25 X 25 PKG,
1.27MM PITCH, WITH CAP ZONES

DOCUMENT NO: 98ARE10530D

REV: A

CASE NUMBER: 1504-02

22 APR 2005

STANDARD: JEDEC MO-156 ABJ

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

2. ALL DIMENSIONS IN MILLIMETERS.



3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.



4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.



6. CAUTION MUST BE TAKEN NOT TO SHORT EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

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